

CATEGORY	DESCRIPTION	P/N #
CONNECTOR	Modular Jack, 10P8C, 1x1PORT	MJ562208-BX11-BRF1

REV.	ECN NO	DESCRIPTION	REVISED	DATE
A01		New Release	Kelly	2009.9.16

NOTES:

MATERIAL:

- 1.HOUSING MATERIAL :GLASS FILLED POLYESTER(UL94V-0).
- 2.CONTACT MATERIAL :PHOSPHOR BRONZE $\phi 0.46\text{mm}$ (C5100).
- 3.PLATING :GOLD PLATING OVER NICKEL.
- 4.SHIELD: COPPER ALLOY 0.20mm THICKNESS PLATING NI.

ELECTRICAL:

- 1.VOLTAGE RATING :125 VAC RMS.
- 2.CURRENT RATING :1.5 AMP.
- 3.CONTACT RESISTANCE :50 MILLIOHMS MAX.
- 4.INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC.
- 5.DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN.

MECHANICAL:

- 1.DURRABILITY :750 CYCLES MIN.
- 2.PCB RETENTION PRE-SOLDER :1 LB MIN.

ENVIRONMENTAL:

- 1.STORAGE : -40°C TO +85°C.
2. OPERATION : 0°C TO 70°C.

MATES WITH MODULAR PLUG CONFORMING TO FCC PART 68,SUBPART F.

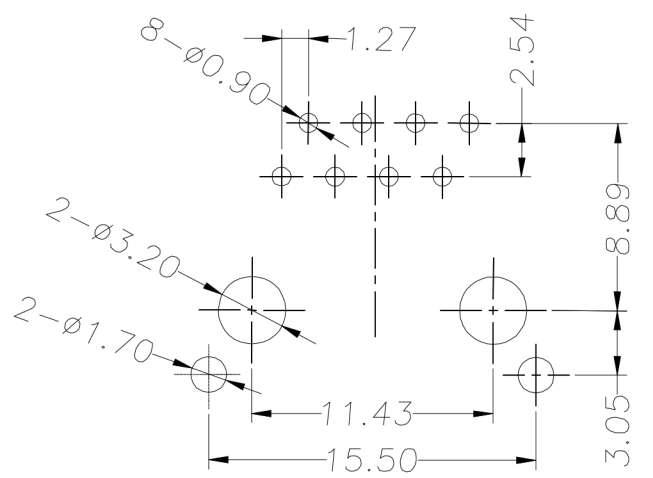
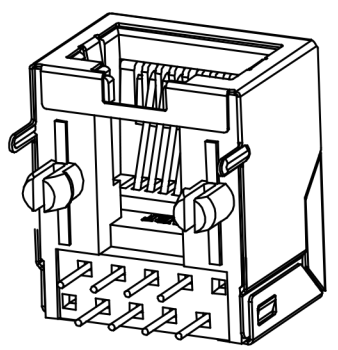
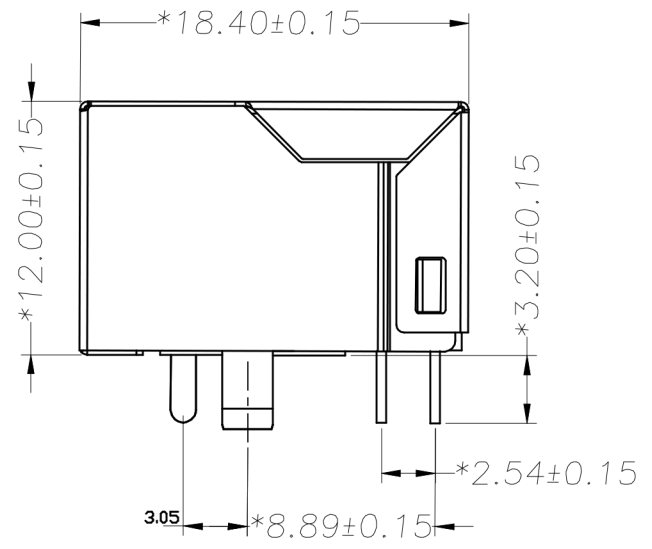
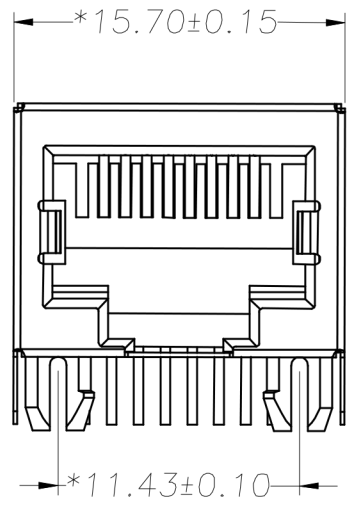
PART NUMBER:

Part No.:

MJ562208-BX11-BRF1

Material & Plating

X	Terminal Plating
0	Au 1u" Plating
1	Au 3u" Plating
2	Au 6u" Plating
3	Au 15u" Plating
4	Au 30u" Plating
5	Au 50u" Plating



PC Board Layout

贵州省合曜电子科技有限公司
 GuiZhouSheng HeYao Electronic Technology Co.,Ltd

UNLESS OTHERWISE SPECIFIED TOLERANCES	SCALE:1/1	UNIT: mm	DWG.NO: WI-061-751
	SIZE: A3	PAGE:1 OF 1	
DECIMALS: X :±0.5 X.X :±0.3 X.XX :±0.2	APPROVED BY Tony	ANGLES: X :±2° X.X :±1°	CHECKED BY Bill
			PREPARED BY Kelly
CUSTOMER COPY			